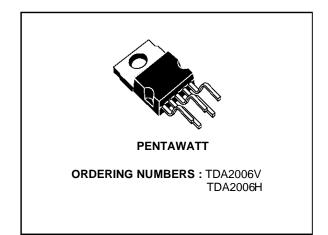


# TDA2006

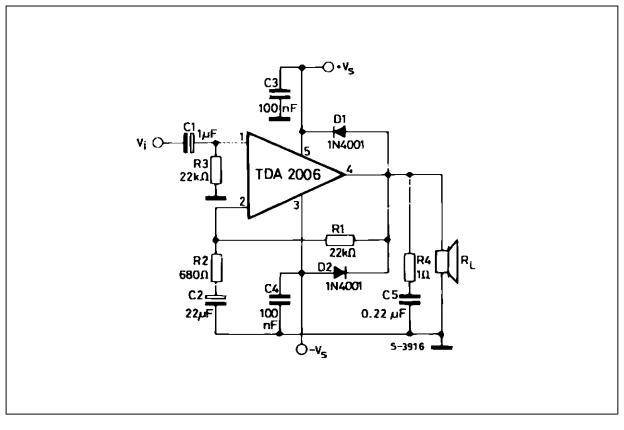
## **12W AUDIO AMPLIFIER**

## DESCRIPTION

The TDA2006 is a monolithic integrated circuit in Pentawatt package, intended for use as a low frequency class "AB" amplifier. At  $\pm 12V$ , d = 10 % typically it provides 12W output power on a 4 $\Omega$  load and 8W on a 8 $\Omega$ . The TDA2006 provides high output current and has very low harmonic and cross-over distortion. Further the device incorporates an original (and patented) short circuit protection system comprising an arrangement for automatically limiting the dissipated power so as to keep the working point of the output transistors within their safe operating area. A conventional thermal shutdown system is also included. The TDA2006 is pin to pin equivalent to the TDA2030.

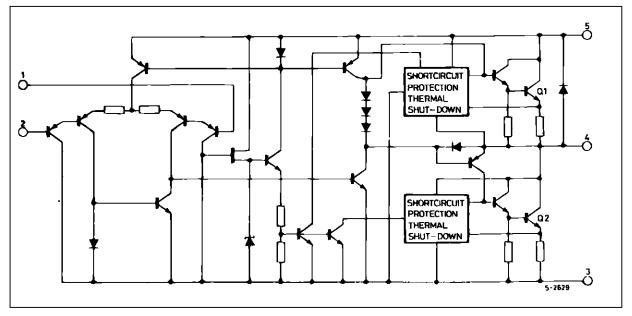


### **TYPICAL APPLICATION CIRCUIT**



## TDA2006

## SCHEMATIC DIAGRAM



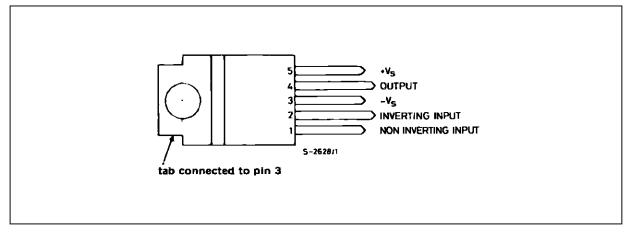
## **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit	
Vs	Supply Voltage	± 15	V	
Vi	Input Voltage	Vs		
Vi	Differential Input Voltage	± 12	V	
lo	Output Peak Current (internaly limited)	3	A	
Ptot	Power Dissipation at T <sub>case</sub> = 90 °C	20	W	
T <sub>stg</sub> , T <sub>j</sub>	Storage and Junction Temperature	– 40 to 150	°C	

## THERMAL DATA

Symbol	Parameter	Value	Unit
Rth (j-c)	Thermal Resistance Junction-case Max	3	°C/W

## **PIN CONNECTION**





## **ELECTRICAL CHARACTERISTICS**

(refer to the test circuit ;  $V_S = \pm 12V$ ,  $T_{amb} = 25^{\circ}C$  unless otherwise specified)

Symbol	bol Parameter Test Conditions		Min.	Тур.	Max.	Unit
Vs	Supply Voltage		± 6		± 15	V
ld	Quiescent Drain Current	$V_s = \pm 15V$		40	80	mA
I <sub>b</sub>	Input Bias Current	$V_s = \pm 15V$		0.2	3	μΑ
Vos	Input Offset Voltage	$V_s = \pm 15V$		± 8		mV
I <sub>OS</sub>	Input Offset Current	$V_s = \pm 15V$		± 80		nA
Vos	Output Offset Voltage	$V_s = \pm 15V$		± 10	± 100	mV
Po	Output Power	$d = 10\%, f = 1 \text{kHz}$ $\begin{array}{c} R_L = 4\Omega\\ R_L = 8\Omega \end{array}$	6	12 8		W
d	Distortion	$ \begin{array}{l} {\sf P}_{o} = 0.1 \ \text{to} \ 8{\sf W},  {\sf R}_{\sf L} = 4\Omega, \ f = 1 \text{kHz} \\ {\sf P}_{o} = 0.1 \ \text{to} \ 4{\sf W},  {\sf R}_{\sf L} = 8\Omega, \ f = 1 \text{kHz} \end{array} $		0.2 0.1		% %
Vi	Input Sensitivity	$ \begin{array}{l} P_{o} = 10W,  R_{L} = 4\Omega,  f = 1kHz \\ P_{o} = 6W,  R_{L} = 8\Omega,  f = 1kHz \end{array} $	200 220			mV mV
В	Frequency Response (- 3dB)	$P_o = 8W, R_L = 4\Omega$	20Hz to 100kHz			z
Ri	Input Resistance (pin 1)	f = 1kHz	0.5	0.5 5		MΩ
Gv	Voltage Gain (open loop)	f = 1kHz		75		dB
Gv	Voltage Gain (closed loop)	f = 1kHz	29.5	30	30.5	dB
e <sub>N</sub>	Input Noise Voltage	B (- 3dB) = 22Hz to 22kHz, $R_L = 4\Omega$		3	10	μV
i <sub>N</sub>	Input Noise Current	B (- 3dB) = 22Hz to 22kHz, $R_L = 4Ω$ 80		80	200	pА
SVR	Supply Voltage Rejection	$R_{L} = 4\Omega, R_{g} = 22k\Omega, f_{ripple} = 100Hz$ (*)	40	50		dB
ld	Drain Current	$\label{eq:Po} \begin{array}{l} P_{o} = 12W,  R_{L} = 4\Omega \\ P_{o} = 8W,  R_{L} = 8\Omega \end{array}$		850 500		mA mA
Tj	Thermal Shutdown Junction Temperature				145	°C

(\*) Referring to Figure 15, single supply.



G-4166 ନ (₩) d = 10 % f = 1KHz 16 RL= 4.0 12 RL= A 8 4 0 12 14 ±V<sub>5</sub>(V) 10 6 ß

Figure 1 : Output Power versus Supply Voltage

Figure 3 : **Distortion versus Frequency** 

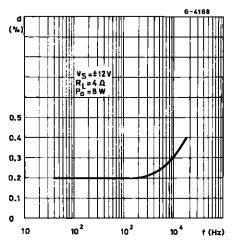


Figure 5 : Sensitivity versus Output Power

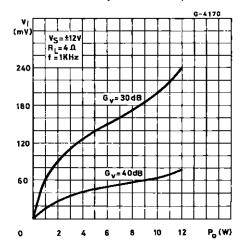


Figure 2 : **Distortion versus Output Power** 

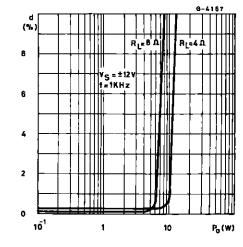


Figure 4: Distortion versus Frequency

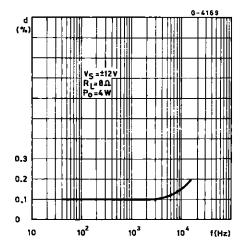


Figure 6: Sensitivity versus Output Power

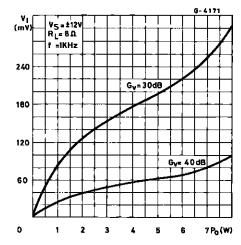




Figure 7 : Frequency Response with different values of the rolloff Capacitor C8 (see Figure 13)

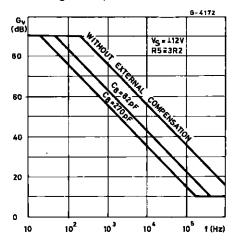


Figure 9 : Quiescent Current versus Supply Voltage

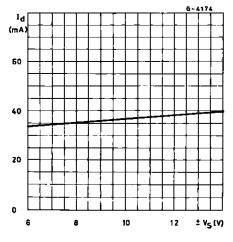


Figure 11 : Power Dissipation and Efficiency versus Output Power

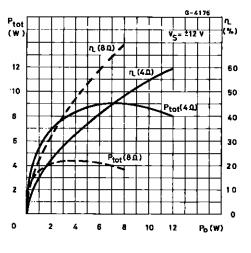


Figure 8 : Value of C8 versus Voltage Gain for different Bandwidths (see Figure 13)

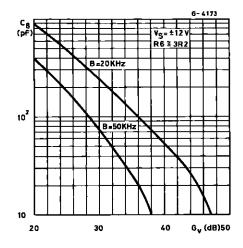


Figure 10 : Supply Voltage Rejection versus Voltage Gain

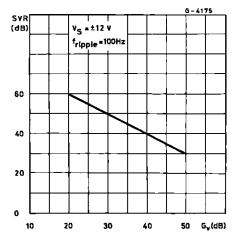
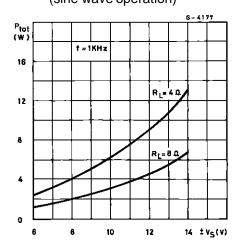


Figure 12 : Maximum Power Dissipation versus Supply Voltage (sine wave operation)





## TDA2006

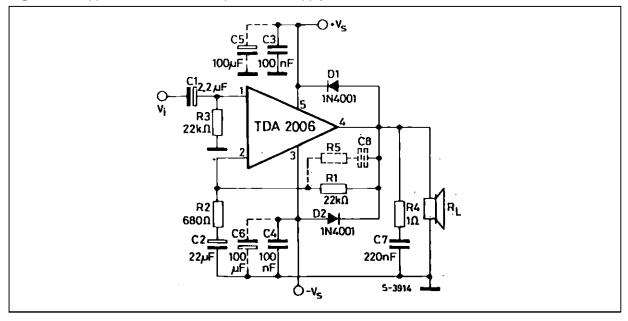
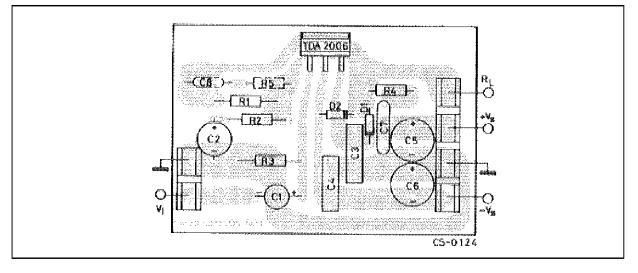


Figure 13 : Application Circuit with Spilt Power Supply







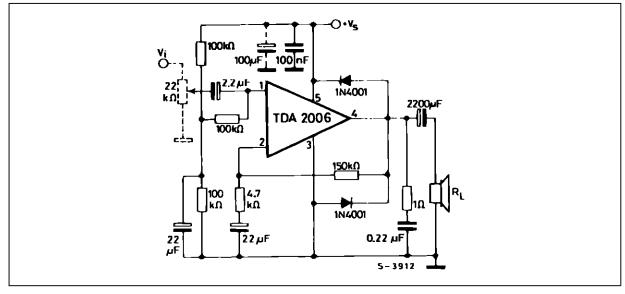
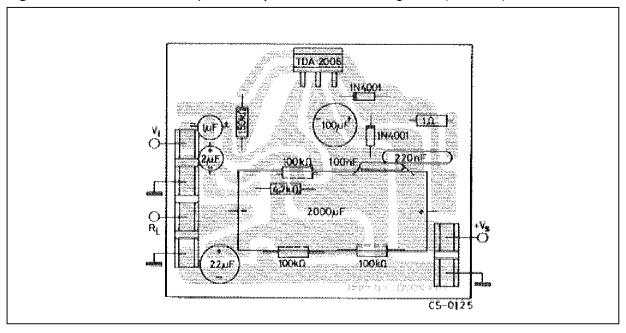
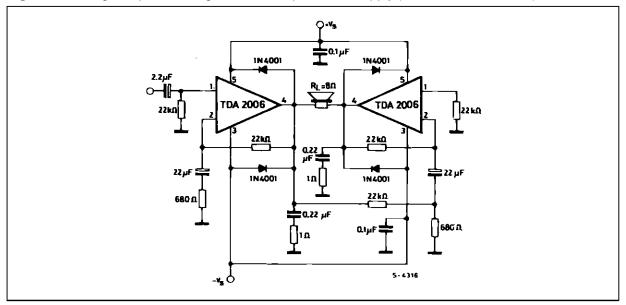


Figure 15 : Application Circuit with Single Power Supply











## PRACTICAL CONSIDERATIONS

### **Printed Circuit Board**

The layout shown in Figure 14 should be adopted by the designers. If different layout are used, the ground points of input 1 and input 2 must be well decoupled from ground of the output on which a rather high current flows.

#### **Assembly Suggestion**

No electrical isolation is needed between the pack-

age and the heat-sink with single supply voltage configuration.

## **Application Suggestion**

The recommended values of the components are the ones shown on application circuits of Figure 13. Different values can be used. The table 1 can help the designers.

Component	Recommanded Value	Purpose	Larger Than Recommanded Value	Smaller Than Recommanded Value		
R1	22 kΩ	Closed Loop Gain Setting	Increase of Gain	Decrease of Gain (*)		
R <sub>2</sub>	680 Ω	Closed Loop Gain Setting	Decrease of Gain (*)	Increase of Gain		
R <sub>3</sub>	22 kΩ	Non Inverting Input Biasing	Increase of Input Impedance	Decrease of Input Impedance		
R <sub>4</sub>	1 Ω	Frequency Stability	Danger of Oscillation at High Frequencies with Inductive Loads			
R <sub>5</sub>	3 R <sub>2</sub>	Upper Frequency Cut-off	Poor High Frequencies Attenuation	Danger of Oscillation		
C <sub>1</sub>	2.2 μF	Input DC Decoupling		Increase of Low Frequencies Cut-off		
C <sub>2</sub>	22 μF	Inverting Input DC Decoupling		Increase of Low Frequencies Cut-off		
C <sub>3</sub> C <sub>4</sub>	0.1 μF	Supply Voltage by Pass Dar		Danger of Oscillation		
C <sub>5</sub> C <sub>6</sub>	100 μF	Supply Voltage by Pass		Danger of Oscillation		
C <sub>7</sub>	0.22 μF	Frequency Stability		Danger of Oscillation		
C <sub>8</sub>	<u>1</u> 2πBR <sub>1</sub>	Upper Frequency Cut-off	Lower Bandwidth	Larger Bandwidth		
D <sub>1</sub> D <sub>2</sub>	1N4001	To Protect the Device Against Output Voltage Spikes.				

#### Table 1

(\*) Closed loop gain must be higher than 24dB.



## SHORT CIRCUIT PROTECTION

The TDA2006 has an original circuit which limits the current of the output transistors. Figure 18 shows that the maximum output current is a function of the collector emitter voltage ; hence the output transistors work within their safe operating area (Figure 19).

This function can therefore be considered as being peak power limiting rather than simple current limiting.

It reduces the possibility that the device gets damaged during an accidental short circuit from AC output to ground.

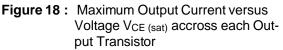
## THERMAL SHUT DOWN

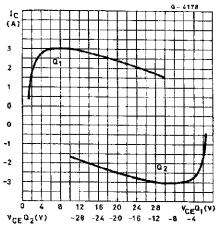
The presence of a thermal limiting circuit offers the following advantages :

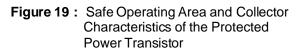
- an overload on the output (even if it is permanent), or an above limit ambient temperature can be easily supported since the T<sub>i</sub> cannot be higher than 150°C.
- the heatsink can have a smaller factor of safety compared with that of a conventional circuit. There is no possibility of device damage due to high junction temperature.

If for any reason, the junction temperature increases up to 150  $^{\circ}\!C$ , the thermal shutdown simply reduces the power dissipation and the current consumption.

The maximum allowable power dissipation depends upon the size of the external heatsink (i.e. its thermal resistance); Figure 22 shows the dissipable power as a function of ambient temperature for different thermal resistances.







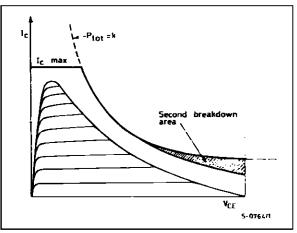
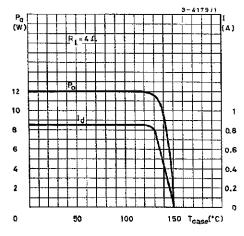
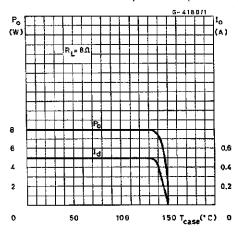


Figure 20 : Output Power and Drain Current versus Case Temlperature ( $R_L = 4\Omega$ )



**Figure 21 :** Output Power and Drain Current versus Case Temlperature ( $R_L = 8\Omega$ )



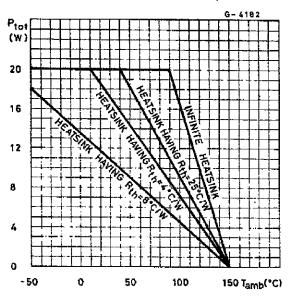


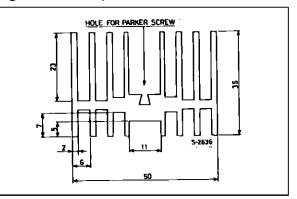
Figure 22 : Maximum Allowable Power Dissipation versus Ambient Temperature

## **DIMENSION SUGGESTION**

The following table shows the length of the heatsink in Figure 23 for several values of  $P_{tot}$  and  $R_{th}$ .

P <sub>tot</sub> (W)	12	8	6
Lenght of Heatsink (mm)	60	40	30
R <sub>th</sub> of Heatsink (°C/W)	4.2	6.2	8.3

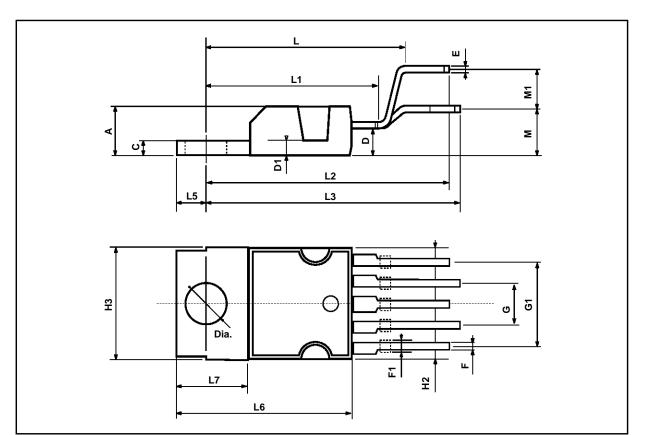
Figure 23 : Example of Heatsink





DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP. MA	
А			4.8			0.189
С			1.37			0.054
D	2.4		2.8	0.094		0.11
D1	1.2		1.35	0.047		0.05
Е	0.35		0.55	0.014		0.022
F	0.8		1.05	0.031		0.04
F1	1		1.4	0.039		0.05
G		3.4		0.126	0.134	0.142
G1		6.8		0.260	0.268	0.276
H2			10.4			0.409
H3	10.05		10.4	0.396		0.409
L		17.85			0.703	
L1		15.75			0.620	
L2		21.4			0.843	
L3		22.5			0.886	
L5	2.6		3	0.102		0.118
L6	15.1		15.8	0.594		0.622
L7	6		6.6	0.236		0.26
Μ		4.5			0.177	
M1		4			0.157	
Dia	3.65		3.85	0.144		0.15

## PENTAWATT PACKAGE MECHANICAL DATA





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